AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior listings of claims presented in the application.

Claim 1 (currently amended): A laminate for an HDD suspension comprising a stainless layer, a polyimide resin layer, and a conductive layer, wherein a thickness of the conductive layer is 10 μm or less, and a surface roughness (Ra) of the conductive layer is 0.15 μm or less.

Claim 2 (original): The laminate for an HDD suspension as described in claim 1, wherein the conductive layer is an alloyed copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

Claim 3 (canceled).

Claim 4 (currently amended): A production process of a laminate for an HDD suspension, wherein a laminate comprising a stainless layer, a polyimide resin layer, and a conductive layer is produced by using ~~the~~a conductive layer having a thickness of larger than 10 μm, and thereafter only the conductive layer is subjected to chemical etching to thereby reduce a thickness of the conductive layer to 10 μm or less.

Claim 5 (original): The production process of a laminate for an HDD suspension as described in claim 4, wherein the conductive layer is an alloyed copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

Claim 6 (original): The production process of a laminate for an HDD suspension as described in claim 4, wherein the laminate after subjected to chemical etching is subjected to supersonic treatment in an alkaline solution.

Claim 7 (original): The production process of a laminate for an HDD suspension as described in claim 5, wherein the laminate after subjected to chemical etching is subjected to supersonic treatment in an alkaline solution.

Claim 8 (currently amended): The production process of a laminate for an HDD suspension as described in ~~any of claims~~claim ~~4 to 6~~, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.

Claim 9 (new): The production process of a laminate for an HDD suspension as described in claim 5, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.

Claim 10 (new): The production process of a laminate for an HDD suspension as described in claim 6, wherein the conductive layer after subjected to chemical etching has a surface roughness (Ra) of 0.15 μm or less.